CST100N03D N-Ch 30V Fast Switching MOSFETs

- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

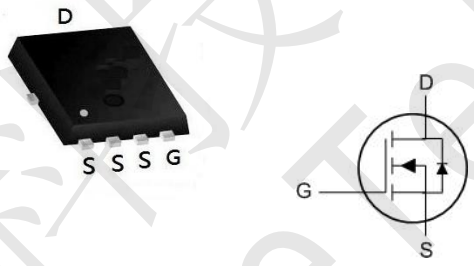
CST100N03D Product Summary

BVDSS	RDSON	ID
30V	3.5mΩ	100A

CST100N03D Description

The CST100N03D is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.
The CST100N03D meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

CST100N03D PDFN3333-8L Pin Configuration



CST100N03D Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		10s	Steady State	
V_{DS}	Drain-Source Voltage	30		V
V_{GS}	Gate-Source Voltage	±20		V
I_D@T_C=25℃	Continuous Drain Current, V_{GS} @ 10V[1]	100		A
I_D@T_C=100℃	Continuous Drain Current, V_{GS} @ 10V[1]	50		A
I_D@T_A=25℃	Continuous Drain Current, V_{GS} @ 10V[1]	30	19	A
I_D@T_A=70℃	Continuous Drain Current, V_{GS} @ 10V[1]	25	16	A
I_{DM}	Pulsed Drain Current[2]	162		A
EAS	Single Pulse Avalanche Energy[3]	144.7		mJ
I_{AS}	Avalanche Current	53.8		A
P_D@T_C=25℃	Total Power Dissipation[4]	62.5		W
P_D@T_A=25℃	Total Power Dissipation[4]	6	2.42	W
T_{STG}	Storage Temperature Range	-55 to 175		℃
T_J	Operating Junction Temperature Range	-55 to 175		℃

CST100N03D Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient [1]	---	62	℃/W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient [1] (t ≤10s)	---	25	℃/W
$R_{\theta JC}$	Thermal Resistance Junction-Case[1]	---	2.4	℃/W

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CST100N03D Electrical Characteristics (T_J=25℃ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	V_{GS}=0V,I_D=250μA	30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} =30V, V_{GS} = 0V,	-	-	1.0	μA
I_{GSS}	Gate to Body Leakage Current	V_{DS} =0V,V_{GS} = ±20V	-	-	±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}= V_{GS}, I_D=250μA	1.0	1.5	2.5	V
$R_{DS(on)}$	Static Drain-Source on-Resistance note3	V_{GS} =10V, I_D =30A	-	3.5	4.7	mΩ
		V_{GS} =4.5V, I_D =20A	-	6.0	10	
C_{iss}	Input Capacitance	V_{DS} =15V, V_{GS} =0V, f = 1.0MHz	-	2100	-	pF
C_{oss}	Output Capacitance		-	326	-	pF
C_{rss}	Reverse Transfer Capacitance		-	282	-	pF
Q_g	Total Gate Charge	V_{DS} =15V, I_D =30A, V_{GS} =10V	-	45	-	nC
Q_{gs}	Gate-Source Charge		-	3	-	nC
Q_{gd}	Gate-Drain(“Miller”) Charge		-	15	-	nC
$t_{d(on)}$	Turn-on Delay Time	V_{DS}=15V, I_D=30A, R_{GEN}=3Ω, V_{GS} =10V	-	21	-	ns
t_r	Turn-on Rise Time		-	32	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	59	-	ns
t_f	Turn-off Fall Time		-	34	-	ns
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	50	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	200	A
V_{SD}	Drain to Source Diode Forward Voltage	V_{GS} = 0V, I_S=30A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I_F=20A,dI/dt=100A/μs	-	15	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	4	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: T_J=25℃, V_G=10V, R_G=25Ω，L=0.5mH，I_{AS}=18.4A

3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

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Figure1: Output Characteristics

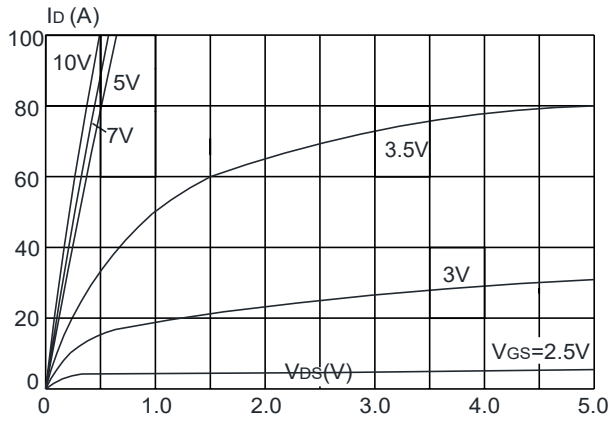

Figure 2: Typical Transfer Characteristics

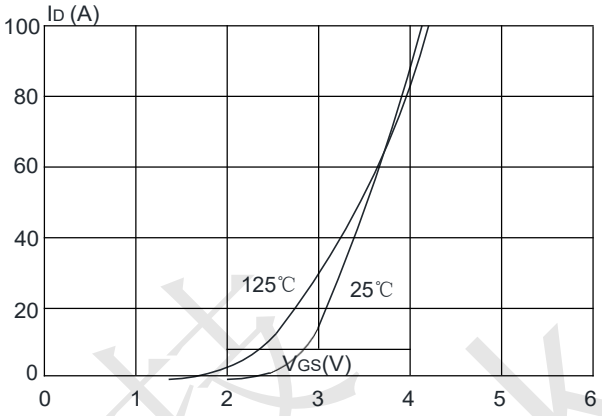

Figure 3: On-resistance vs. Drain Current

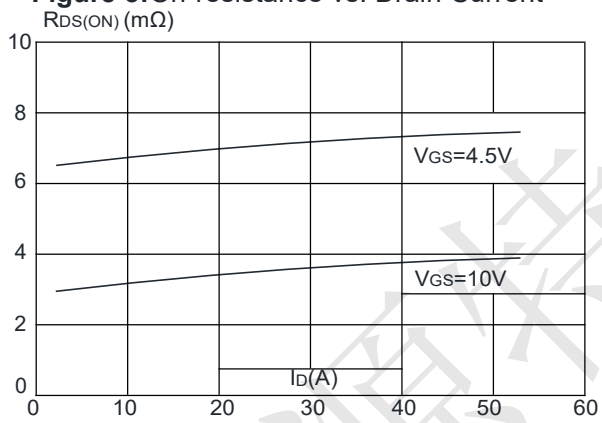

Figure 4: Body Diode Characteristics

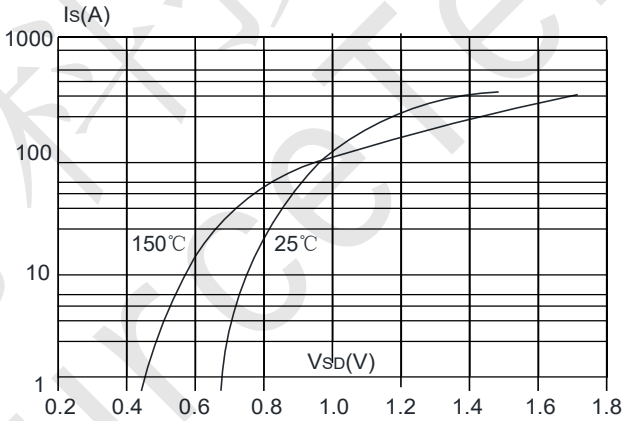

Figure 5: Gate Charge Characteristics

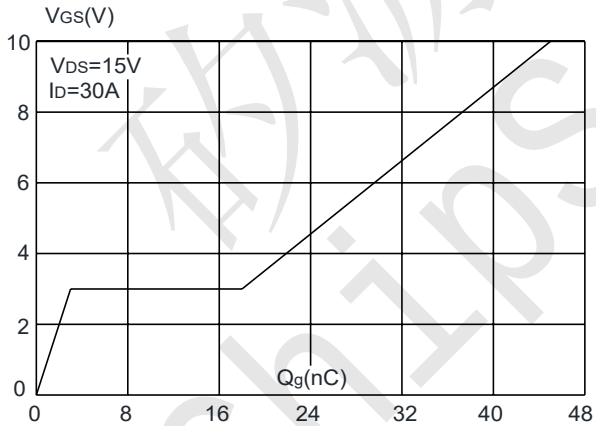

Figure 6: Capacitance Characteristics

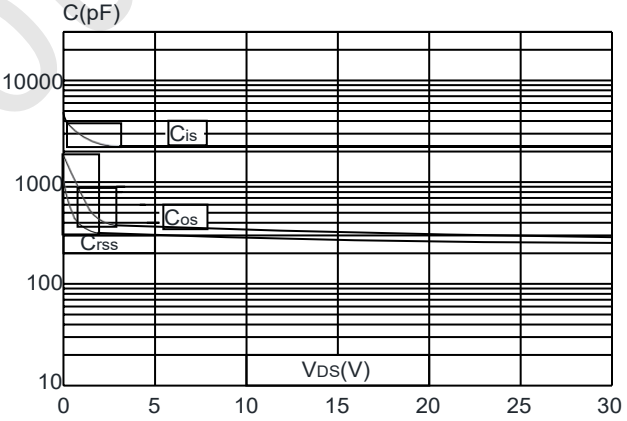

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Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

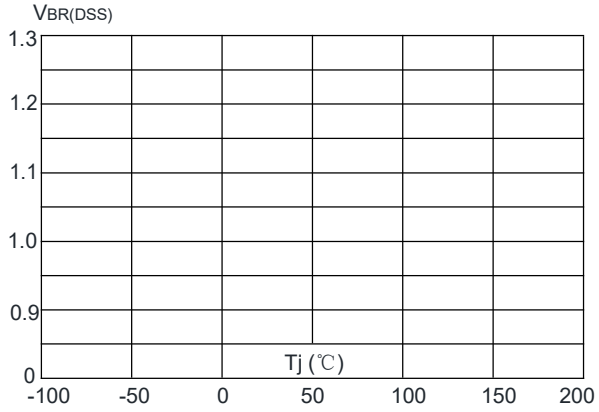


Figure 8: Normalized on Resistance vs. Junction Temperature

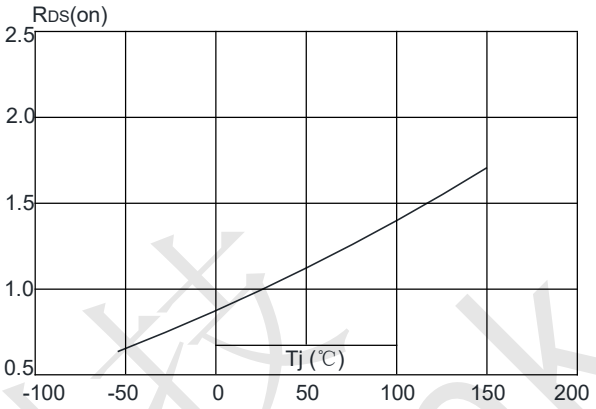


Figure 9: Maximum Safe Operating Area

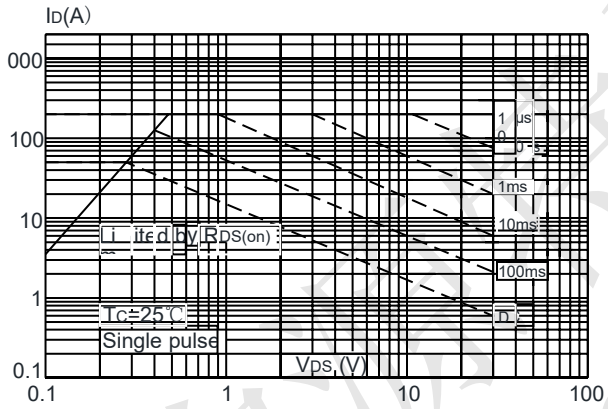


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

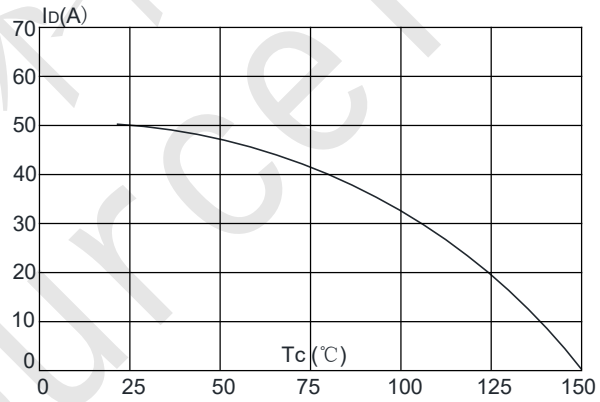
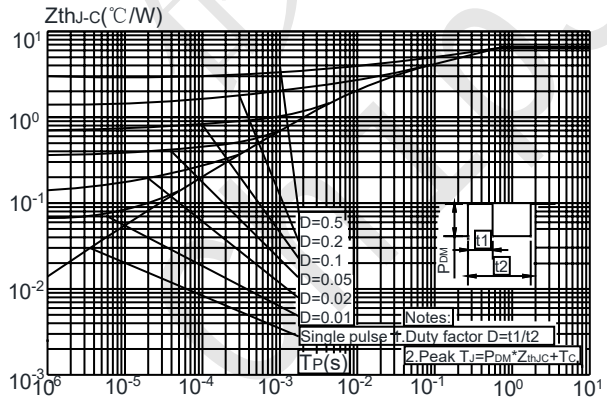


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case (PDFN3.3*3.3-8L)



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CST100N03D Test Circuit

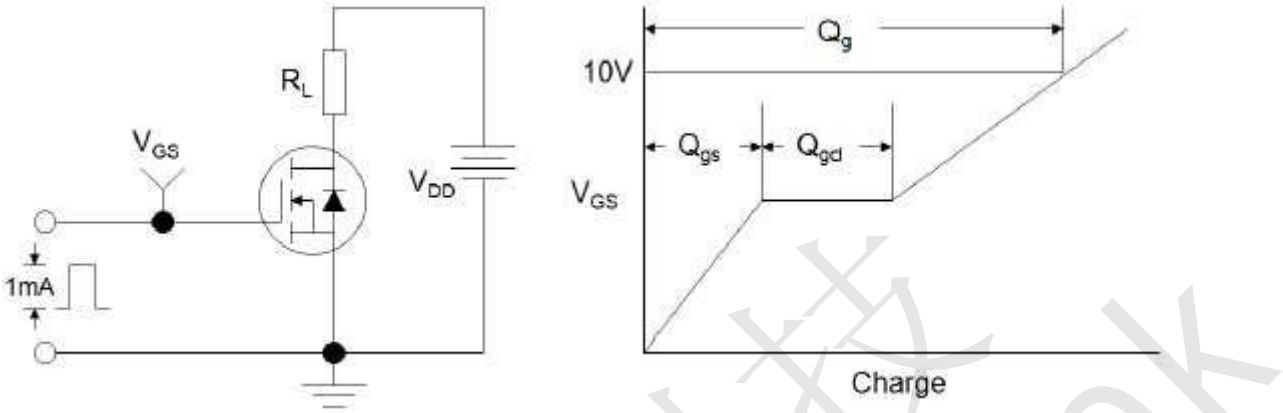


Figure1:Gate Charge Test Circuit & Waveform

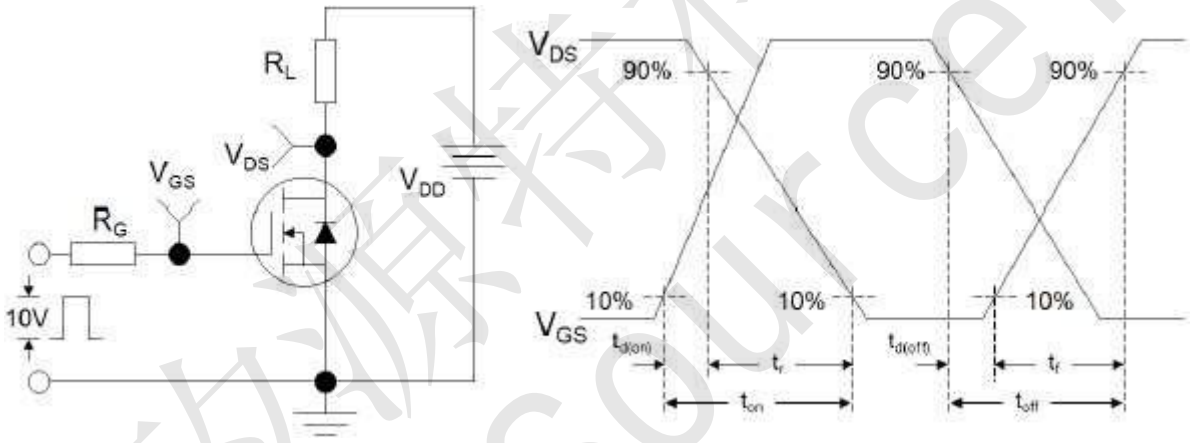


Figure 2: Resistive Switching Test Circuit & Waveforms

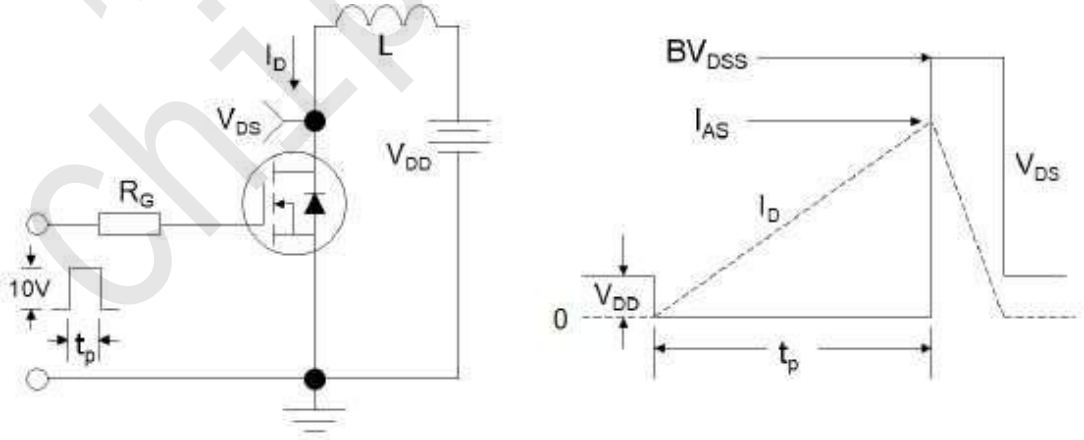
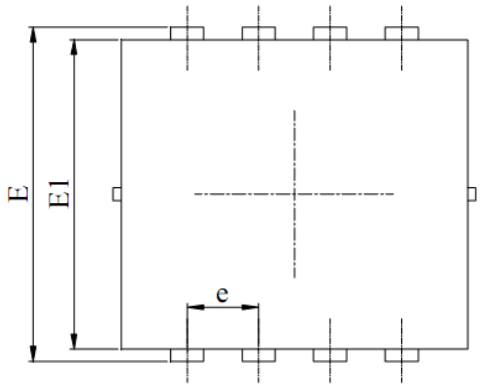
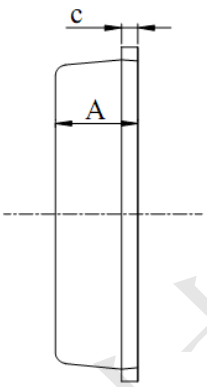


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

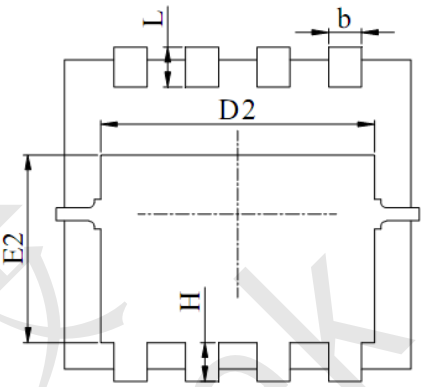
CST100N03D Package Mechanical Data-PDFN3333-8L-Single



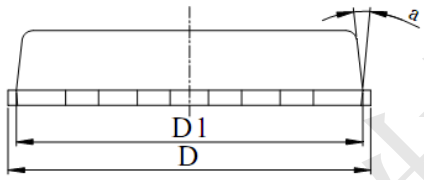
Top View



Side View



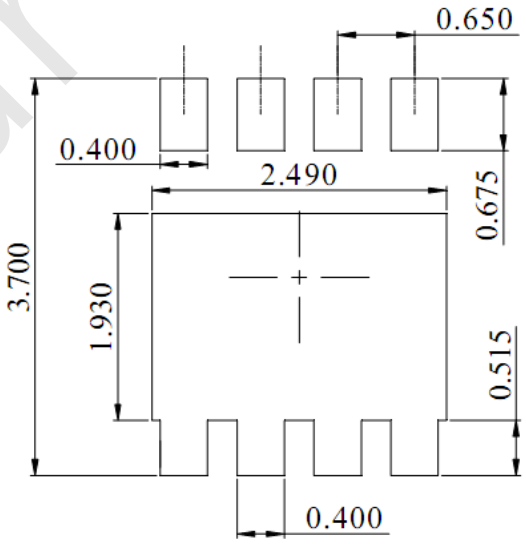
Bottom View



Front View

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
2. ALL DIMNESIONS IN MILLIMETER (ANNGLE IN DEGREE).
3. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	0.70	0.75	0.80
b	0.25	0.30	0.35
c	0.10	0.20	0.25
D	3.00	3.15	3.25
D1	2.95	3.05	3.15
D2	2.39	2.49	2.59
E	3.20	3.30	3.40
E1	2.95	3.05	3.15
E2	1.70	1.80	1.90
e		0.65 BSC	
H	0.30	0.40	0.50
L	0.25	0.40	0.50
a	---	---	15°



DIMENSIONS:MILLIMETERS